

Strong adhesive transfer tapes UT5440

Features

- Adhesive tape with lower environmental impact with UV curable manufacturing method (non solvent adhesive coating process).
- High heat resistance; can be used in environments of up to 100°C.
- Maximum bonding strength is about four times as strong as G series (the conventional company products). Excellent adhesion to glass and metallic surfaces.

Structure



Main component	Acrylic
Carrier	Non-carrier
Color	Transparent
Adhesive thickness (µm)	About 400
Release paper thickness (µm)	About 150
Bonding strength (N/20mm) *	51
St'd size (width & length)	480 × 700mm

^{* 90°} peeling strength

Suitable use

- Ideal for bonding plastics and metals used in wood panels in automobile interiors.
- Ideal for applications requiring waterproofing, oil resistance and air tightness.

Technical data

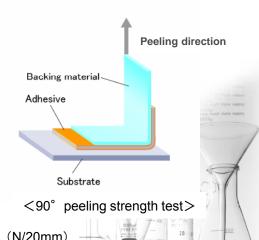
1. Bonding strength on various type of substrate (90° peeling)

<Test piece condition>
Tape width: 20mm

Bonding condition: One stroke with 2-kg roller Measuring condition: 23°C±5°C 60%±20%RH

Peeling speed: 300mm/min

Backing material: 40µm Aluminum foil [Left at RT for one day before measurement]



<Results>

				(14/20111111)
Substrate	SUS	ABS	PC	AL
90° peeling strength	51.0	25.5	22.8	26.7

UT5440 TDS-040













2. Holding power at different temperatures

<Test piece condition>

Substrate: Stainless steel plate (SUS304)

Bonding area: 25mm × 25mm

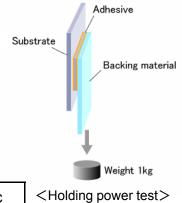
Bonding condition: One stroke with 2-kg roller

Backing material: 40µm Aluminum foil

[Left at RT for one hour and then at each temperature for 30 minutes

before measurement]

[Creep length after one hour application of 1-kg load]



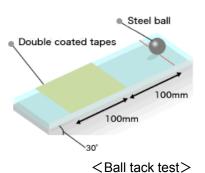
<Results>

VI toballoy				
Measurement temperature	40°C	80°C	100°C	
Creep length (mm)	0.8	1.3	2.7	

3. Ball tack test (J. Dow method)

<Results>

Ball tack test (Ball No.)	16 to 18
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4. Curved surface bending

<Test piece condition>

Substrate ①: Aluminum plate 0.5mm thickness × 20mm × 150mm

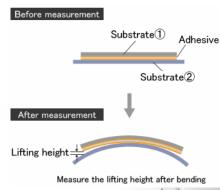
Substrate ②: ABS plate 2mm thickness × 25mm × 200mm

Bonding condition: One stroke with 2-kg roller

Measuring condition: 50°C

[Left at RT for 24 hours, then lifting height of the edge after the

elapsed time is measured]



and a firgh tendency to

<Curved surface bending test>

<Results>

	Substrate	1 hour	3 hours	5 hours	8 hours	24 hours
Lifting height (mm)	ABS/AL	0	0	0	0	1.2

Revision in Oct, 2012

Note on the characteristic data given— Data on the characteristics of the products described in this catalog are based on the results of evaluations carried out by the company This does not guarantee that the characteristics of the product conform with your usage environment. Before use, review the usage conditions based on evaluation data obtained from the equipment and substrates actually used.

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